

2021 International Symposium on VLSI Design, Automation and Test (2021 VLSI-DAT)

The 2021 International Symposium on VLSI Design, Automation and Test will be held on April 19-22, 2021 at the Ambassador Hotel, Hsinchu, Taiwan. Original and unpublished papers on all aspects of VLSI Design, Automation and Test are solicited, including but not limited to:

ANALOG DESIGN	DIGITAL DESIGN	SOC	EDA	TEST	AI APPLICATIONS
Biomedical Circuits	Communication Baseband Designs	CPU, DSP and Multicore Architectures	Analog EDA	3D IC and Interposer-Based IC Test	AI ASIC Architecture
Energy-Harvesting and Power Management Circuits	Digital Circuits and ASICs	Embedded System and Software	Design for Manufacturability	Design-for-Testability and BIST	AI Learning Model (Algorithms)
Sensor and Interface Circuits	Hardware Security and Trust	Multimedia Processing Designs	Design Verification	Memory Test	AI for EDA
Memristive and Neuromorphic Circuits	Low Voltage & Low Power Circuits Design	SOC and NOC Architectures	EDA for Microfluidic Biochips	On-Chip Monitoring	Compiler for AI Chips
RF, Analog and Mixed Signal Circuits	Memory Circuits and Systems	System-in-Package Designs	Electronic System Level Design	RF, Analog and Mixed-Signal Test	Integrated Development Environment for AI
Security Circuits for IoT and AI	Wired and IO Design		Hardware/Software Co-Design	Silicon Debug and Diagnosis	New Service Using AI
Ultra Low-Power Circuits and Systems			Logic and Behavioral Synthesis	SOC and System Level Test	
			Physical Design and Verification	Yield and Reliability Enhancement	
			Modeling and Simulation	Test Generation and Compression	
			Power/Thermal Estimation and Optimization	Test Standards	

➔ GENERAL INSTRUCTIONS

- Prospective authors must submit a self-contained paper with figures and tables electronically through the conference website [Submit your paper!](#) by **October 15, 2020 (23:59 GMT+8)**.
- **The length of a submitted paper must be 2-4 pages. Any submissions not adhering to the length constraint will be returned immediately without review.**
- In addition to the paper and camera-ready manuscript [CLICK HERE](#), the submission should also include an 80~100-word ABSTRACT, which will be published in the advance and final program if the paper

Second Call for Papers

is accepted.

- VLSI-DAT adopts the DOUBLE BLIND REVIEW process; please **DO NOT reveal** your name(s) or affiliation(s) anywhere in the submitted manuscript for the first paper submission.
- Before submitting your abstract/paper, please review the information on IEEE Intellectual Property Rights at <http://www.ieee.org/web/publications/rights/index.html>
- The notices of acceptance will be sent out to authors on December 31, 2020.
- Any changes on title and author list or withdraw after acceptance must be approved by Technical Program Co-Chairs.
- **For an accepted paper to be published in the proceedings, one of its co-author(s) MUST pay the FULL REGISTRATION fee by February 28, 2021 23:59 (GMT+8) and attend the symposium to present the paper. Note that each accepted paper shall be accompanied by a different full registration; that is, two full registrations are required for presenting two papers even if the presenter is the same.**
- Presentation of accepted papers at the symposium must be in English and will be limited to 18 minutes with an additional 2 minutes for Q&A. The final manuscripts of all accepted papers will be published as submitted in the proceedings.
- No-show papers will not be included in the symposium proceedings and will not be submitted to the IEEE Xplore database.

➔ STUDENT SUBSIDY

MORE INFO

- All students are entitled to get a discount of up to 85% on the registration fee.
- Financial supports are available for full-time student presenters living outside of Taiwan.

➔ BEST PAPER AWARD

MORE INFO

Two best papers will be selected this year through a rigorous evaluation process, which is conducted by the program committee and session chairs.

➔ IMPORTANT DATES

Note: all are based on Taiwan time (GMT+8).

Paper Submission Deadline	Oct. 15, 2020
Notification of Acceptance	Dec. 31, 2020
Final Paper (IEEE compatible version) Submission Deadline	Jan. 31, 2021
Author Registration Deadline	Feb. 28, 2021

2021 Technical Program Co-Chairs

Prof. Chung-Ho Chen

National Cheng Kung University,
Taiwan

E-mail: chchen@mail.ncku.edu.tw

Dr. Racy Cheng

Industrial Technology Research Institute
Taiwan

E-mail: racy.cheng@itri.org.tw

Prof. Atsushi Takahashi

Tokyo Institute of Technology,
Japan

E-mail: atsushi@ict.e.titech.ac.jp